

IC TESTING APPARATUS AND METHODS

ABSTRACT

[042] Methods, devices, and systems of the invention provide improved semiconductor device testing with firm tester-to-device interface and increased contact area. A test probe (24, 58) associated with ATE (18) is configured to substantially correspond to a probe receptacle (38) of a test board (16) or semiconductor device (10). Upon insertion of the test probe (24, 58) into the probe receptacle (38), areas of staunch electrical contact (34) between the probe receptacle (38) and probe (24, 58) facilitate measuring an electrical signal.